

CLAIMS:

(amended August 2, 2005)

1. An aerogel molded part containing an inorganic filler containing hollow spheres and having a thermal conductivity of up to $0.5 \text{ Wm}^{-1}\text{K}^{-1}$.
2. The aerogel molded part according to claim 1, characterized in that said aerogel is a silica aerogel, a carbon aerogel or an organic aerogel, especially a resorcinol/formaldehyde aerogel.
3. The aerogel molded part according to claim 1, characterized in that said hollow spheres consist of glass.
4. The aerogel molded part according to claim 1, characterized in that the thermal conductivity of the filler is up to $0.1 \text{ Wm}^{-1}\text{K}^{-1}$.
5. The aerogel molded part according to claim 1, characterized in that said aerogel contains a filler in an amount of from 70% to 90% by volume.
6. The aerogel molded part according to claim 1, characterized in that the thermal conductivity of the molded part is lower than the thermal conductivity of the filler-free aerogel.
7. A process for the preparation of an aerogel molded part according to any of claims 1 to 6, comprising the following steps:
 - a. preparation of a sol;
 - b. mixing the sol with a filler;
 - c. gelling of the sol into a gel; and
 - d. Drying of the gel.
8. The process according to claim 7, characterized in that the resulting aerogel molded part is pyrolyzed.